



### **DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

BVDSS	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
	20mΩ @ V <sub>GS</sub> = 10V	6.9A
30V	27mΩ @ V <sub>GS</sub> = 4.5V	5.8A

## **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

## **Features**

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN3033LSDQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

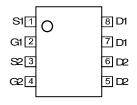
https://www.diodes.com/quality/product-definitions/

### **Mechanical Data**

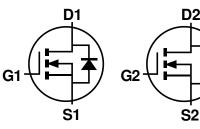
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound;
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe;
   Solderable per MIL-STD-202, Method 208 (23)
- Weight: 0.072grams (Approximate)







Top View



N-Channel MOSFET

N-Channel MOSFET

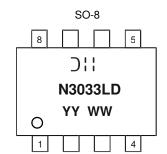
### Ordering Information (Note 4)

Part Number	Case	Packaging	
DMN3033LSDQ-13	SO-8	2,500/Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



O!! = Manufacturer's Marking
N3033LD = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 20 = 2020)
WW = Week (01 to 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Chara	acteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	30	V	
Gate-Source Voltage		V <sub>GSS</sub>	±20	V	
Drain Current (Note 5)	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lo	6.9 5.8	А
Pulsed Drain Current (Note 6)			IDM	30	Α

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P <sub>D</sub>	2	W
Thermal Resistance, Junction to Ambient	Reja	62.5	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

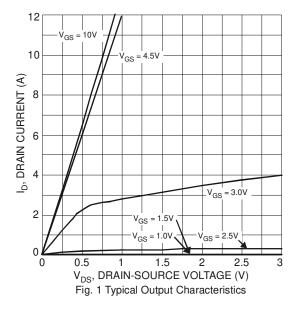
# **Electrical Characteristics** (@TA = +25°C, unless otherwise specified.)

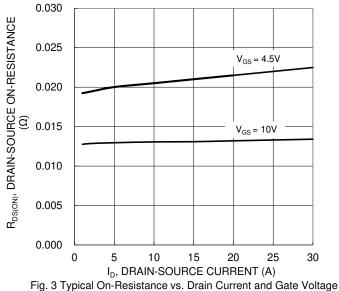
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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	30		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	100	nA	$V_{DS} = 30V$ , $V_{GS} = 0V$	
Gate-Source Leakage	loop	_	_	±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	
Gale-Source Leakage	Igss			1	μΑ	$V_{GS} = \pm 25V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	2.1	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D		13	20 27	mΩ	$V_{GS} = 10V, I_{D} = 6.9A$	
Static Drain-Source On-nesistance	R <sub>DS(ON)</sub>	_	22		11122	$V_{GS} = 4.5V, I_{D} = 5A$	
Forward Transconductance	<b>g</b> fs	_	7	_	S	$V_{DS} = 5V, I_{D} = 6.9A$	
Diode Forward Voltage (Note 7)	$V_{SD}$	0.5	_	1.2	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	725	_	pF	15)()(	
Output Capacitance	Coss	_	114	_	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V f = 1MHz	
Reverse Transfer Capacitance	Crss	_	92	_	pF		
Gate Resistance	R <sub>G</sub>		0.89		Ω	$V_{GS} = 0V$ , $V_{DS} = 0V$ , $f = 1MHz$	
SWITCHING CHARACTERISTICS (Note 8)							
Total Gate Charge	$Q_g$		- 6.4 13	_	nC	$V_{GS} = 4.5V, V_{DS} = 15V, I_{D} = 5A$	
Total date onarge	Оg					$V_{GS} = 10V, V_{DS} = 15V, I_{D} = 6.9A$	
Gate-Source Charge	Qgs	_	1.9	_	nC	$V_{GS} = 4.5V, V_{DS} = 15V, I_{D} = 6.9A$	
Gate-Drain Charge	$Q_{gd}$		3.2	_	nC	$V_{GS} = 4.5V, V_{DS} = 15V, I_D = 6.9A$	
Turn-On Delay Time	td(ON)	_	11	_	ns		
Turn-On Rise Time	tR	_	7	_	ns	$V_{DD} = 15V, V_{GS} = 10V,$	
Turn-Off Delay Time	tD(OFF)	_	63	_	ns	$R_D = 1.8\Omega$ , $R_G = 6\Omega$	
Turn-Off Fall Time	tF	_	30	_	ns	]	

Notes: 5. Device mounted on 2 oz. Copper pads on FR-4 PCB with  $R_{\theta JA} = 62.5^{\circ} C/W$ .

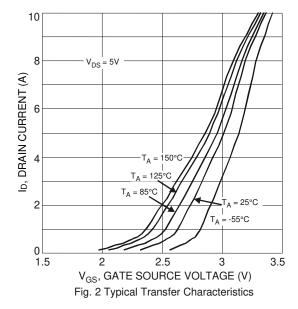
Delive midth ≤10μS, Duty Cycle ≤1%.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.







1.6 1.5 1.4 R<sub>DS(ON)</sub>, DRAIN-TO-SOURCE RESISTANCE (NORMALIZED) V<sub>GS</sub> = 10V 1.3  $I_{D} = 6.9A$ 1.2 V<sub>GS</sub> = 4.5V 1.1  $I_D = 5A$ 1.0 0.9 8.0 0.7 0.6 25 50 75 100 125 -50



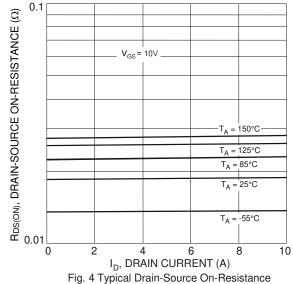
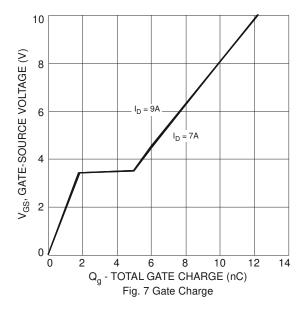


Fig. 5 On-Resistance Variation with Temperature

T<sub>.I</sub>, JUNCTION TEMPERATURE (°C)





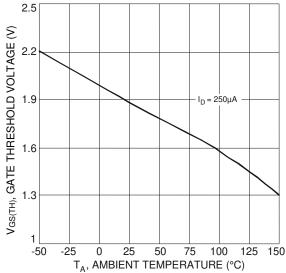
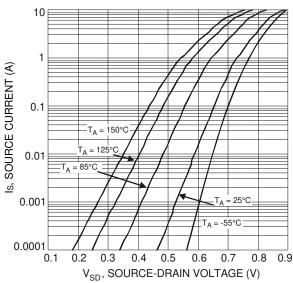


Fig. 8 Gate Threshold Variation vs. Ambient Temperature



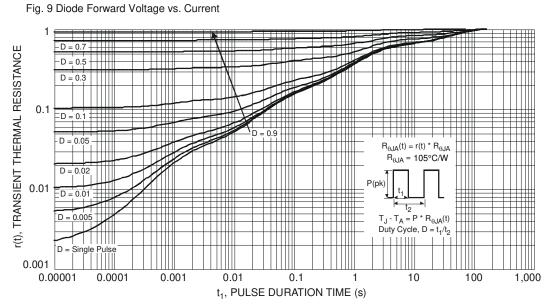


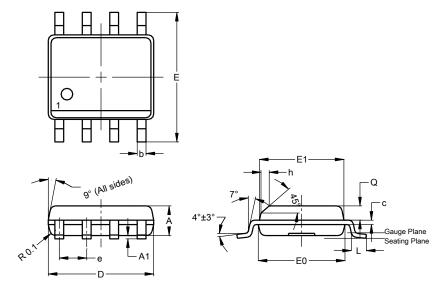
Fig. 10 Transient Thermal Response



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



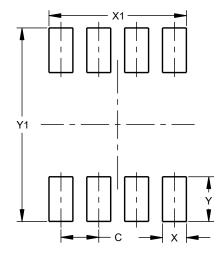


SO-8				
Dim	Min	Max	Тур	
Α	1.40	1.50	1.45	
<b>A</b> 1	0.10	0.20	0.15	
b	0.30	0.50	0.40	
С	0.15	0.25	0.20	
D	4.85	4.95	4.90	
Ε	5.90	6.10	6.00	
E1	3.80	3.90	3.85	
E0	3.85	3.95	3.90	
е			1.27	
h			0.35	
L	0.62	0.82	0.72	
Q	0.60	0.70	0.65	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

**SO-8** 



Dimensions	Value (in mm)		
С	1.27		
Х	0.802		
X1	4.612		
Υ	1.505		
Y1	6.50		



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